

REMARKS/ARGUMENTS

Favorable reconsideration of this application in view of the above amendments and following remarks is respectfully requested.

Claims 11-20 are pending in this application. By this amendment, Claims 11 and 16-18 are amended; and no claims are canceled or added herewith. It is respectfully submitted that no new matter is added by this amendment.

In the outstanding Office Action, Claims 16-18 were rejected under 35 U.S.C. § 112, first and second paragraphs; Claims 11-15 were rejected under 35 U.S.C. § 102(b) as anticipated by U.S. Patent No. 3,895,218 to Cooke; Claims 11-15 were rejected under 35 U.S.C. § 102(b) as anticipated by U.S. Patent No. 4,453,669 to Karla; Claims 16-20 were rejected under 35 U.S.C. § 103(a) as unpatentable over Cooke and further in view of U.S. Patent No. 5,299,726 to Sauer; and Claim 16-18 and 20 were rejected under 35 U.S.C. § 103(a) as unpatentable over Karla in view of Sauer.

With respect to the rejection of Claims 16-18 under 35 U.S.C. § 112, first paragraph and second paragraphs, Claims 16-18 are amended by the present amendment. Further, Applicants note that the thin-film system 2 discussed on at least page 6, lines 20-29 of the present specification includes at least one electrically conducting functional layer. The specification discusses that the functional layer is preferably made of metal however, there is no teaching that the functional layer must be made of metal. Accordingly, withdrawal of the rejection of the claims under 35 U.S.C. § 112, first and second paragraphs is respectfully requested.

With respect to the rejection of the claims under 35 U.S.C. § 102 and § 103, those rejections are respectfully traversed. It is respectfully submitted that the applied art does not teach or suggest at least one electroconducting non-transparent contact surface placed on a surface of a pane to connect it by soldering to a connection piece, the contact surface including at least one cutout such that in a region of the soldering location, the at least one

cutout is configured to be at least partially filled with a soldering filler metal, the filler being visible through the pane after the connection piece has been soldered to the contact surface, as claimed in Claim 11.

Instead, Cooke discusses a grid design such as the grid 16 shown in Fig. 2 that includes terminal areas 18 and 20 which overly the silver terminal areas 12 and 14 respectively. Not covered with resist are smaller areas 22 and 24 within the terminal areas 18 and 20. In an etching operation, the areas 22 and 24 of aluminum will be etched away exposing the underlying silver. Subsequent to the application of the resist, the grid pattern is retained and the aluminum on the plate is etched away. The heater plate will then have the exposure of silver through the aluminum terminal areas in the openings 22 and 24.

Karla discusses a strip 4 disposed along vertical edges of the glass pane over the power supply conductors 3. The strip 4 provides a protective layer for the power supply conductors and is made of an electrically insulating material. As shown in Fig. 3, a layer 12 is made of the same material as strip 4 and is disposed on glass pane 1. The power supply conductors 3 and the transitional region 7 of heating conductors 2 are disposed between strip 4 and layer 12. The strip 4 is provided with an opening 13, and layer 12 is provided with an opening 16. In application of the conductive metal, such as silver, forming the conductors, the compound will migrate through window 16 to connect the conductors 3 and the heating conductors 2 to the glass surface.

The features of the claimed invention are not taught in the applied art. Again, Claim 11 recites in part, that the at least one electroconducting non-transparent contact surface placed on a surface of a pane includes at least one cutout such that in a region of the soldering location, the at least one cutout is configured to be at least partially filled with a soldering filler metal visible through the pane after the connection piece has been soldered to the contact surface. In Karla for example, an opening is formed in the electrically insulating strip 4 and layer 12. No opening is formed in the power supply conductors 3. In accordance with

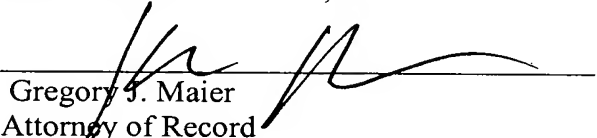
the features of the claimed invention, owing to the fact that at least one observation window is formed in the actual contact surface, which window remains visible through the transparent pane provided with the contact surface after the locations of the connection pieces have been soldered, it is possible to see, by simple visual verification, whether the soldering filler metal has melted and to what extent. Overall, the amount of soldering filler metal and the soldering location will be determined so that, in the event of correct soldering, part of the soldering filler metal flows so as to be optically visible in said observation window, or, depending on the case, so as to make the modification resulting from the melting of the surface structure of the soldering filler metal visible. Accordingly, withdrawal of the rejections of the claims under 35 U.S.C. § 102 and § 103 is respectfully requested.

Consequently, for the reasons discussed in detail above, no further issues are believed to be outstanding in the present application, and the present application is believed to be in condition for formal allowance. Therefore, a Notice of Allowance is earnestly solicited.

Should the Examiner deem that any further action is necessary to place this application in even better form for allowance, the Examiner is encouraged to contact the undersigned representative at the below-listed telephone number.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.



Gregory J. Maier
Attorney of Record
Registration No. 25,599

Customer Number
22850

Tel: (703) 413-3000
Fax: (703) 413 -2220
(OSMMN 08/07)

Kevin M. McKinley
Registration No. 43,794